Power LDMOS transistor Rev. 5 — 7 August 2024

Product profile 1.

1.1 General description

Based on Advanced Rugged Technology (ART), this 2000 W LDMOS RF power transistor has been designed to cover a wide range of applications for ISM, broadcast and communications. The unmatched transistor has a frequency range of 1 MHz to 450 MHz.

Table 1.	Application	information
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Test signal	f	V _{DS}	PL	G _p	η _D
	(MHz)	(V)	(W)	(dB)	(%)
CW	41	65	1600	28.8	79.4
CW pulsed [1][2]	60	55	1250	24.7	85.8
CW pulsed [1][2]	60	65	1690	25.1	83.3
CW pulsed [1][2]	64	65	1785	25.7	84.7
CW [3]	87.5 to 108	60	1730	25.8	85.1

[1] $t_p = 100 \ \mu s; \ \delta = 10 \ \%.$

[2] Performance at 3 dB gain compression level.

[3] Center band performance numbers across the indicated frequency range.

1.2 Features and benefits

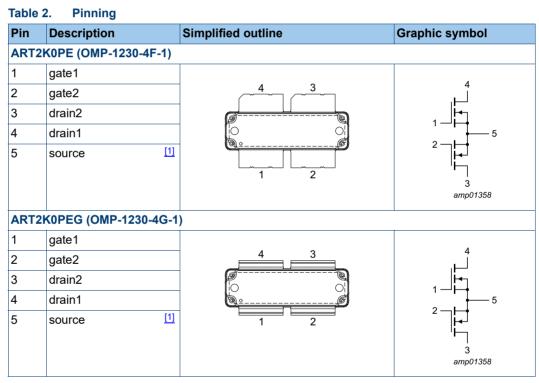
- High breakdown voltage enables class E operation up to V_{DS} = 53 V
- Qualified up to a maximum of V_{DS} = 65 V
- Characterized from 30 V to 65 V to support a wide range of applications
- Integrated dual sided ESD protection enables class C operation and complete switch off of the transistor
- Excellent ruggedness with no device degradation
- High efficiency
- Excellent thermal stability
- Designed for broadband operation
- For RoHS compliance see the product details on the Ampleon website

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1.3 Applications

- Industrial, scientific and medical applications
 - Plasma generators
 - MRI systems
 - Particle accelerators
- Broadcast
 - FM radio
 - VHF TV
- Communications
 - Non cellular communications
 - UHF radar

2. Pinning information



[1] Connected to flange.

3. Ordering information

Table 3.Ordering information

Package name	Orderable part number	12NC	Packing description	Min. orderable quantity (pieces)
OMP-1230-4F-1	ART2K0PEZ	9349 606 96517	Tray; 20-fold; dry pack	60
	ART2K0PEY	9349 606 96518	TR13; 100-fold; 56 mm; dry pack	100
OMP-1230-4G-1	ART2K0PEGZ	9349 606 97517	Tray; 20-fold; dry pack	60
	ART2K0PEGY	9349 606 97518	TR13; 100-fold; 56 mm; dry pack	100

ART2K0PE_ART2K0PEG

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Product data sheet

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage	[1	-	200	V
V _{GS}	gate-source voltage		-9	+13	V
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature	[2	-	225	°C

[1] Specified over lifetime at maximum operating temperature.

[2] Continuous use at maximum temperature will affect the reliability.

5. Thermal characteristics

Table 5.Thermal characteristics

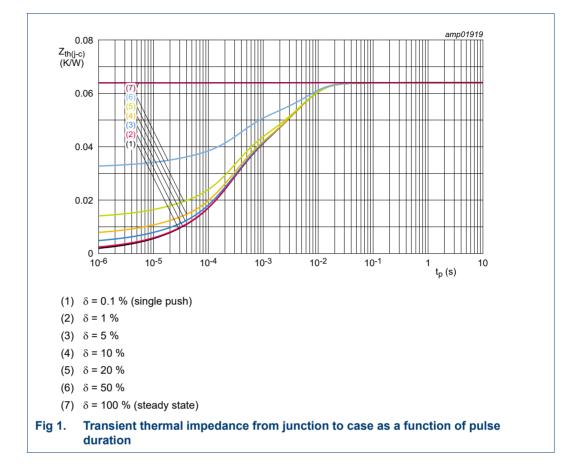
According to standard MIL-STD-883E.

Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-c)}	thermal resistance from junction to case	$T_j = 95 ^{\circ}C$, measured [1][2] under RF condition	0.064	K/W

[1] Refer to application note AN221014 on the Ampleon website.

[2] See Figure 1.

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6. Characteristics

Table 6. DC characteristics

 T_j = 25 °C; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{(BR)DSS}	drain-source breakdown voltage	V _{GS} = 0 V; I _D = 5.5 mA	203	208	-	V
V _{GS(th)}	gate-source threshold voltage	V _{DS} = 20 V; I _D = 550 mA	1.6	2.1	2.6	V
I _{DSS}	drain leakage current	V _{GS} = 0 V; V _{DS} = 65 V	-	-	2.8	μA
I _{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 V;$ $V_{DS} = 20 V$	-	76	-	A
I _{GSS}	gate leakage current	V _{GS} = 11 V; V _{DS} = 0 V	-	-	280	nA
R _{DS(on)}	drain-source on-state resistance	V _{GS} = V _{GS(th)} + 3.75 V; I _D = 19.25 A	-	0.106	-	Ω

Table 7.AC characteristics

 $T_i = 25 \ ^{\circ}C$; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
C _{rs}	feedback capacitance	V _{GS} = 0 V; V _{DS} = 65 V; f = 1 MHz	-	3.27	-	pF
C _{iss}	input capacitance	V _{GS} = 0 V; V _{DS} = 65 V; f = 1 MHz	-	614	-	pF
C _{oss}	output capacitance	V _{GS} = 0 V; V _{DS} = 65 V; f = 1 MHz	-	187	-	pF

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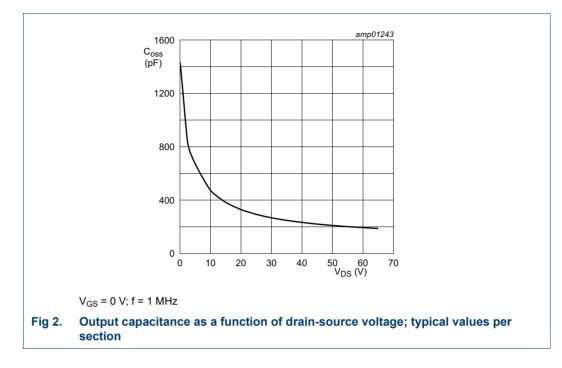


Table 8. RF characteristics

Test signal: pulsed RF; $t_p = 100 \ \mu s$; $\delta = 3 \ \%$; $f = 108 \ MHz$; RF performance at $V_{DS} = 65 \ V$; $I_{Dq} = 50 \ mA \ per \ section$; $T_{case} = 25 \ \ \%$; unless otherwise specified; in a class-AB production test circuit.

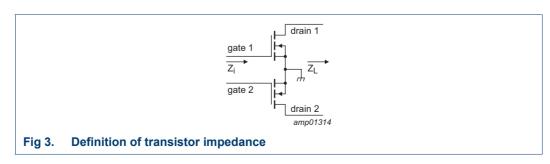
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
G _p	power gain	P _L = 2000 W	26.5	27.7	-	dB
RL _{in}	input return loss	P _L = 2000 W	-	-15	-	dB
η _D	drain efficiency	P _L = 2000 W	68.0	71.7	-	%

7. Test information

7.1 Ruggedness in class-AB operation

The ART2K0PE and ART2K0PEG are capable of withstanding a load mismatch corresponding to VSWR ≥ 65 : 1 through all phases under the following conditions: V_{DS} = 65 V; I_{Dq} = 100 mA per section; P_L = 2000 W pulsed; t_p = 100 µs; δ = 10 %; f = 108 MHz.

7.2 Impedance information



ART2K0PE_ART2K0PEG

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Table 9. Typical push-pull impedance

Simulated Z_i and Z_L device impedance; impedance info at V_{DS} = 65 V and P_L = 2000 W.

f	Z _i	ZL
(MHz)	(Ω)	(Ω)
108	2.4 – j8.7	3.8 + j0.9

7.3 Test circuit

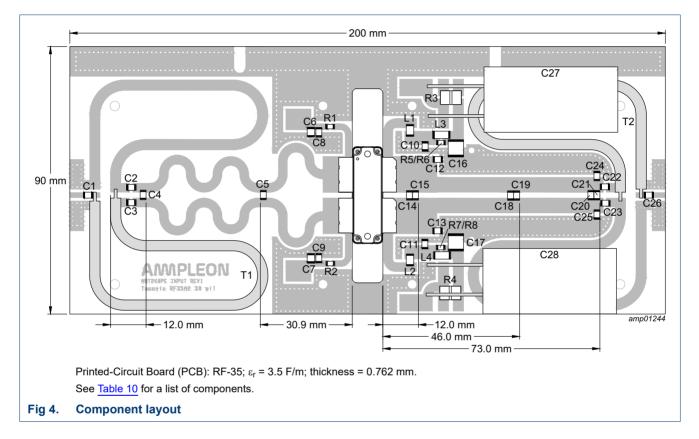


Table 10.List of componentsFor test circuit see Figure 4.

Value Remarks Component Description [1] C1, C26 multilayer ceramic chip capacitor 470 pF [1] C2, C3 multilayer ceramic chip capacitor 68 pF [1] C4 multilayer ceramic chip capacitor 43 pF [1] C5 multilayer ceramic chip capacitor 300 pF C6, C7 4.7 μF, 50 V multilayer ceramic chip capacitor Murata: GRM32ER71H475KA88L [1] C8, C9, C10, C11 multilayer ceramic chip capacitor 820 pF [1] C12, C13 multilayer ceramic chip capacitor 180 pF [1] C14, C15 39 pF multilayer ceramic chip capacitor C16, C17 multilayer ceramic chip capacitor 4.7 μF, 100 V TDK: C5750X7R2A475KT/A [1] C18, C19 multilayer ceramic chip capacitor 56 pF [1] 51 pF C20, C21 multilayer ceramic chip capacitor

ART2K0PE_ART2K0PEG

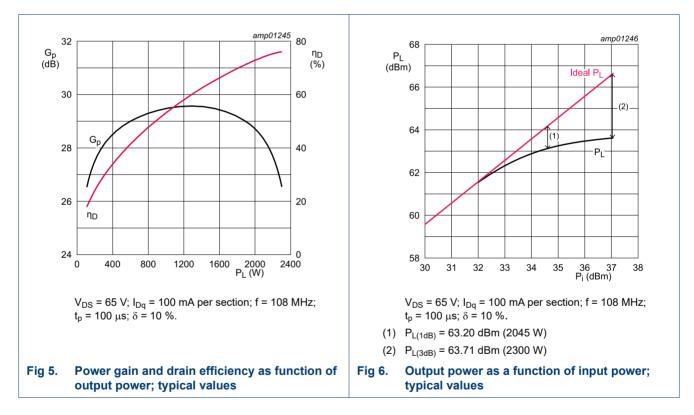
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Power LDMOS transistor

Table 10. List of components ... continued

For test circuit see <u>Figure 4</u> .						
Component	Description	Value	Remarks			
C22, C23	multilayer ceramic chip capacitor	120 pF [1]				
C24, C25	multilayer ceramic chip capacitor	20 pF [1]				
C27, C28	electrolytic capacitor	2200 μF, 100 V				
L1, L2	air inductor	47 nH	Coilcraft: 1515SQ-47N			
L3, L4	air inductor	82 nH	Coilcraft: 1515SQ-82N			
R1, R2	resistor	4.7 kΩ	SMD 1206			
R3, R4	resistor	0.01 Ω	Vishay: WSHP2818			
R5, R6, R7, R8	resistor	9.1 Ω	SMD 1206			
T1, T2	semi rigid coax	50 Ω, 160 mm	EZ141-AL-TP/M17			

[1] American Technical Ceramics type 100B or capacitor of same quality.



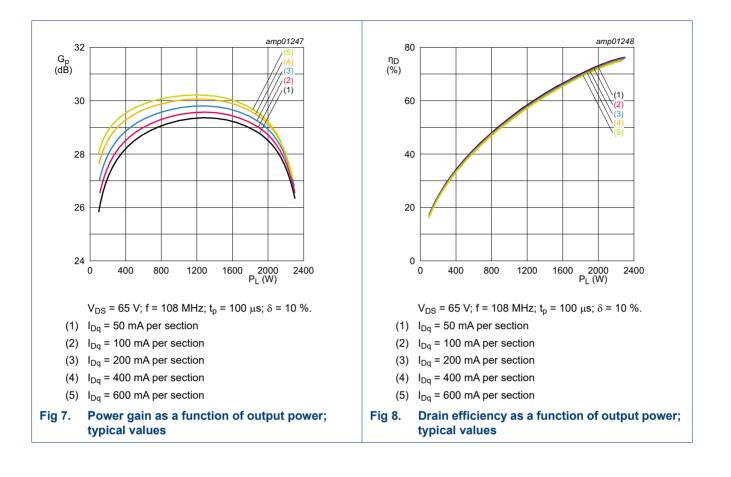
7.4 Graphical data

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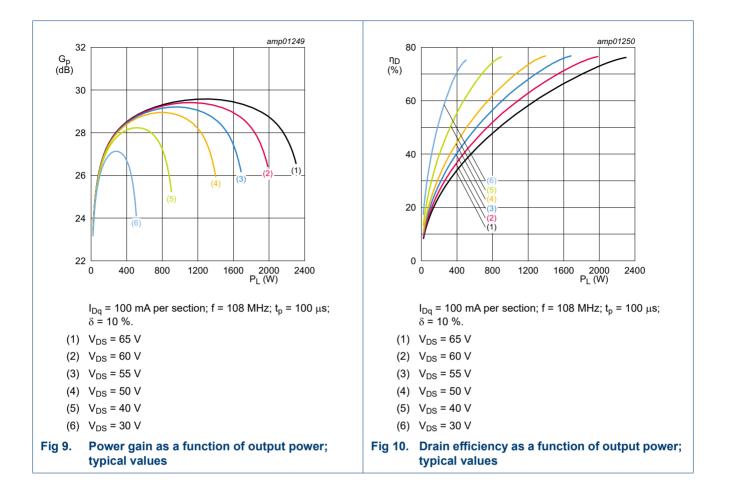
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AMPLEON

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Power LDMOS transistor



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8. Package outline

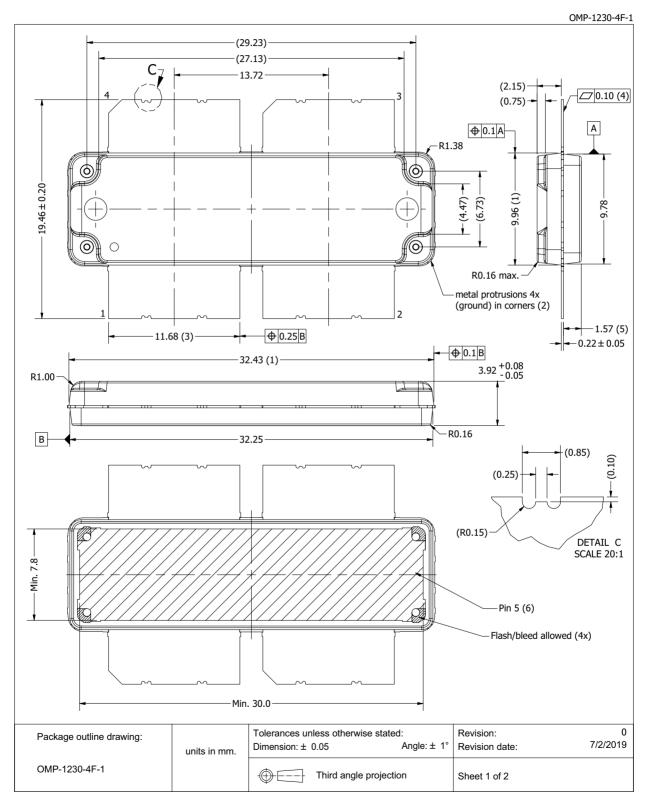


Fig 11. Package outline OMP-1230-4F-1 (sheet 1 of 2)

ART2K0PE_ART2K0PEG

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Power LDMOS transistor

OMP-1230-4F-1

			Drawing Notes				
Items			Description				
	Dimensions are exc	cluding mold protru	usion. All areas located adjacent to the leads have	e a maximum mold protrusion of 0.25			
(1)	mm (per side) and r	nm (per side) and max. 0.62 mm in length.					
	At all other areas th	t all other areas the mold protrusion is maximum 0.15 mm per side. See also detail B.					
(2)	The metal protrusio	e metal protrusion (tie bars) in the corner will not stick out of the molding compound protrusions (detail A).					
(3)	The lead dambar (n	e lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location.					
(4)	The lead coplanarity	y over all leads is (0.1 mm maximum.				
(5)	Dimension is measured	ured from bottom o	of lead to bottom of plastic package.				
(3)	Dimension is measu	ured 0.5 mm from	the edge of the package body.				
(6)	The hatched area ir	ndicates the expos	sed metal heatsink.				
(7)	The leads and expo	osed heatsink are p	plated with matte Tin (Sn).				
88							
			B A lead dambar location				
∙ackage ou	utline drawing:	units in mm.	Lead dambar	Revision: Revision date: 7/2/20			

Fig 12. Package outline OMP-1230-4F-1 (sheet 2 of 2)

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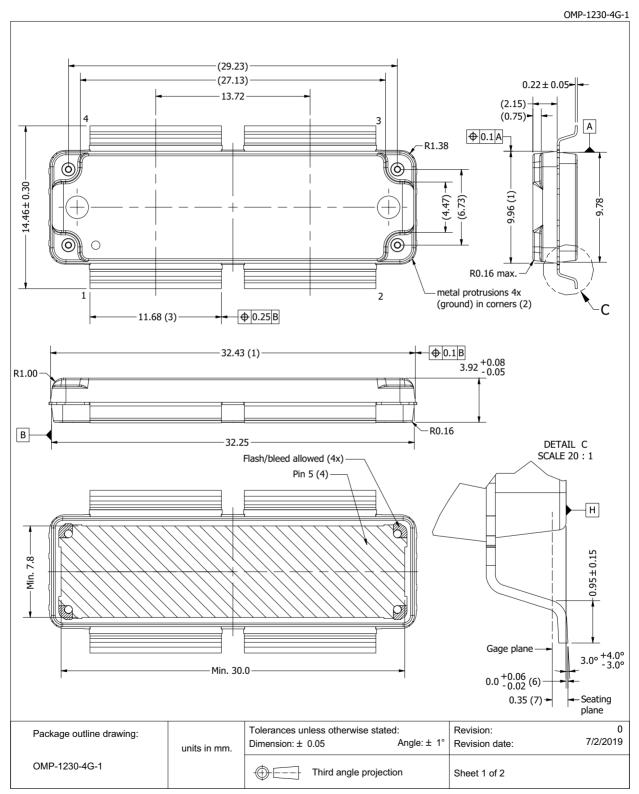


Fig 13. Package outline OMP-1230-4G-1 (sheet 1 of 2)

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Power LDMOS transistor

OMP-1230-4G-1

			Drawing Notes			
Items			Description			
(1)		Dimensions are excluding mold protrusion. Areas located adjacent to the leads have a maximum mold protrusion of 0.25 nm (per side) and 0.62 mm max. in length. At all other areas the mold protrusion is maximum 0.15 mm per side. See also detail B.				
(2)		n (tie bars) in the c	corner will not stick out of the molding compound	protrusions (detail A).		
(3)	The lead dambar (n	netal) protrusions a	are not included. Add 0.14 mm max to the total le	ad dimension at the dambar location.		
(4)	The hatched area in	The hatched area indicates the exposed metal heatsink.				
(5)	The leads and expo	osed heatsink are p	plated with matte Tin (Sn).			
(6)	Dimension is measured with respect to the bottom of the plastic package Datum H. Positive value means that the bottom of the package is higher than the bottom of the lead. Gage plane (foot length) to be measured from the seating plane.					
			Location of metal protrusion (2) B A lead dambar location	DETAIL A SCALE 25 : 1		
			Tolerances unless otherwise stated:	Revision:		
Package ou	utline drawing:	units in mm.	Dimension: \pm 0.05 Angle: \pm 1°	Revision date: 7/2/201		

Fig 14. Package outline OMP-1230-4G-1 (sheet 2 of 2)

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9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

Table 11.ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C2A
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2

10. Abbreviations

Table 12. Abbreviations				
Acronym	Description			
CW	Continuous Wave			
ESD	ElectroStatic Discharge			
FM	Frequency Modulation			
ISM	Industrial, Scientific and Medical			
LDMOS	Laterally Diffused Metal-Oxide Semiconductor			
MRI	Magnetic Resonance Imaging			
RoHS	Restriction of Hazardous Substances			
SMD	Surface Mounted Device			
UHF	Ultra High Frequency			
VHF	Very High Frequency			
VSWR	Voltage Standing Wave Ratio			

11. Revision history

Table 13.Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
ART2K0PE_ART2K0PEG v.5	20240807	Product data sheet	-	ART2K0PE_ART2K0PEG v.4
Modifications:	• <u>Table 10 on</u>	page 6: changed value	row C8	
ART2K0PE_ART2K0PEG v.4	20230907	Product data sheet	-	ART2K0PE_ART2K0PEG v.3
ART2K0PE_ART2K0PEG v.3	20201019	Product data sheet	-	ART2K0PE v.2
ART2K0PE v.2	20200806	Product data sheet	-	ART2K0PE_ART2K0PEG v.1
ART2K0PE_ART2K0PEG v.1	20200114	Objective data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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